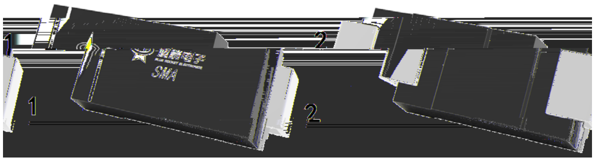
Surface Mount Ultrafast Recovery Rectifier,Reverse Voltage:50 to1000V,Forward Current:1.0A, SMA package.

Glass Passivated Chip Junction High efficiency Lead free in comply with EU R0HS 2011/65/EU directives For surface mounted applications,HF product.

General purpose.



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size

See Marking Instructions.

[redacted]

Parameter	Symbol	Test condition	Rating							Unit
			US1A	US1B	US1D	US1G	US1J	US1K	US1M	
Maximum Instantaneous Forward Voltage	V_F	I_F=1.0A	1.0			1.3	1.65			V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25	5.0							uA
		T_a=125	100							
Maximum Reverse Recovery Time	T_{rr}	I_F=0.5A I_R=1.0A I_{rr}=0.25A	50				75			ns

[redacted]

[redacted]

Fig.1 Forward Current Derating Curve

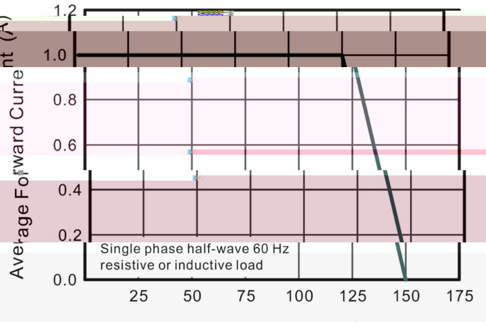


Fig.2 Typical Reverse Characteristics

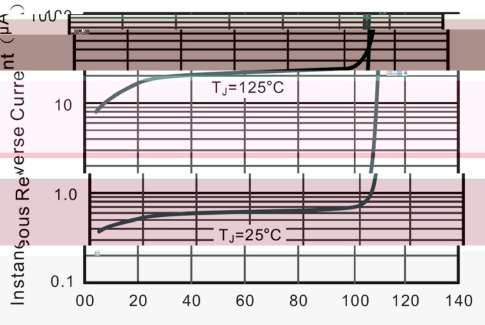


Fig.3 Typical Forward Characteristics

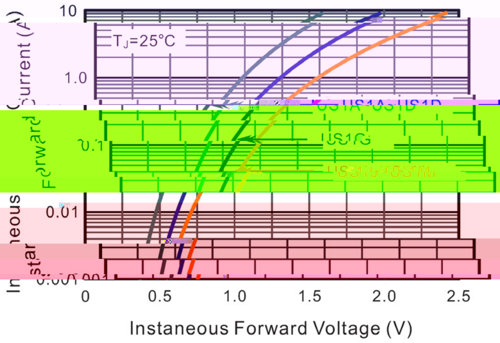


Fig.4 Maximum Non-Repetitive Peak
Forward Surage Current

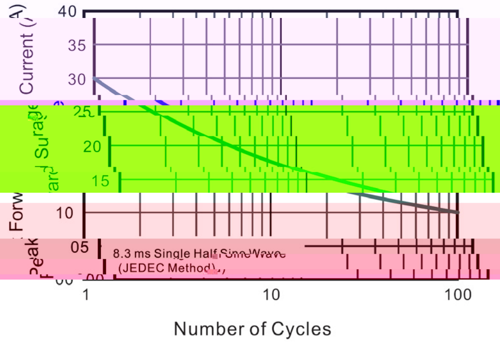


Fig.5- Typical Transient Thermal Impedance

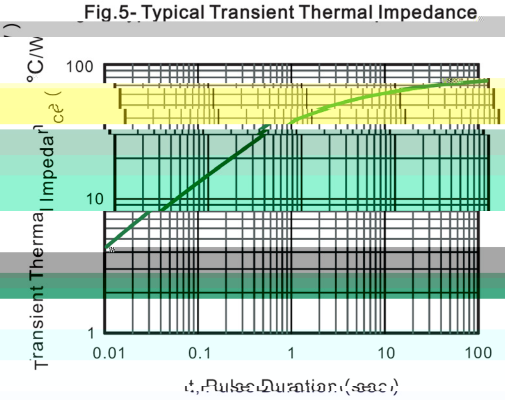
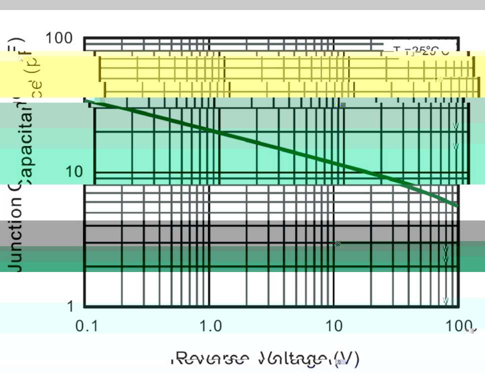
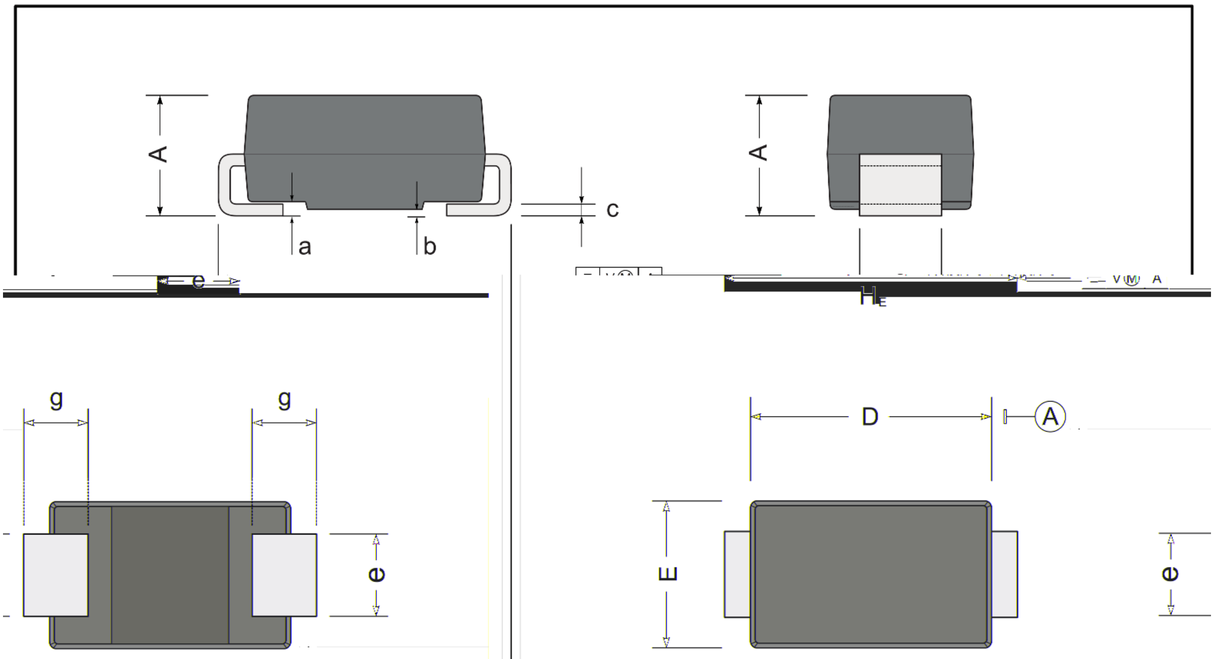


Fig.6 Typical Junction Capacitance

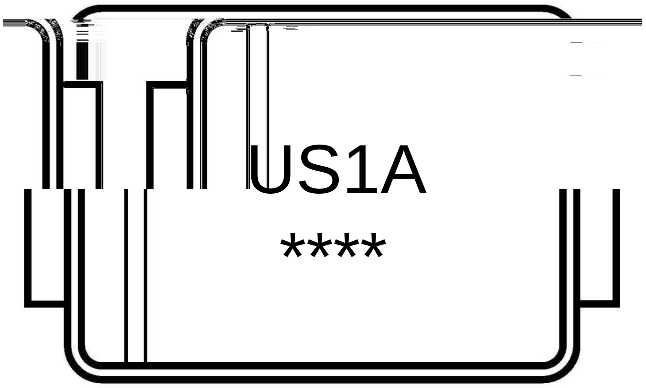


SMA



	e	g	b	a
31	1.6	1.5	0.2	0.3
15	1.3	0.9	0.05	
2	63	59	7.9	12
	51	35	2	

UNIT		A	D	E	H_E	c
mm	max	2.2	4.5	2.7	5.2	0.
	min	1.9	4.0	2.3	4.7	0.
mil	max	87	181	106	205	1
	min	75	157	91	185	



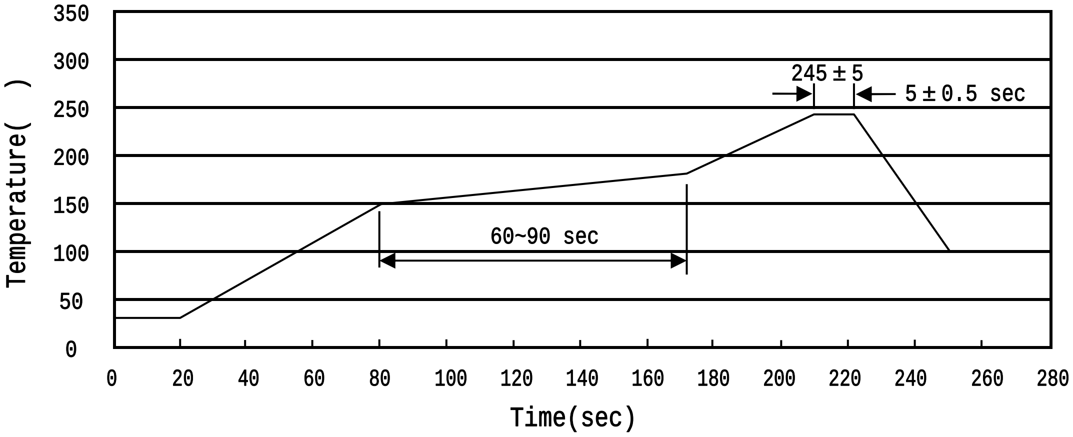
Note:

Product Type Code

Lot No. Code, code change with Lot No

Type number	Marking code
US1A	US1A
US1B	US1B
US1D	US1D
US1G	US1G
US1J	US1J
US1K	US1K
US1M	US1M

Temperature Profile for IR Reflow Soldering(Pb-Free)



	Note:
1 150 180 60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2 245 5 5 0.5sec;	2.Peak Temp.:245 5 , Duration:5 0.5sec.
3 2 10 /sec.	3. Cooling Speed: 2~10 /sec.

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ REEL

Package Type	Units					Dimension		(unit mm^3)
SMA	5,000	2	10,000	7	70,000	13 ×12	336×336×40	380×335×366